EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S30	2	"US 20060175630"	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2008/02/14 17:27
S32	376	S31 and (cavity with (mold$3))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 17:58
S31	6433	(257/720,705,706,707,712,796).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/02/14 17:58
S33	57	S31 and (cavity with (mold$3) with fille$1)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 17:59
S34	33	S33 and (heat near sink)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 18:01
S35	1	S31 and (cavity with (mold$3) with filler)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 18:06
S36	17	S31 and (cavity with (mold$3)) and (mold$3 with filler)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 18:07
S37	1693	S31 and parallel	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 18:34
S38	712	S31 and (((integrated near circuit$2) ic chip die dice semiconductor) with parallel)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 18:35

S39	16	S38 and (((integrated near circuit$2) ic chip die dice semiconductor) with back-to-back)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 18:36
S40	9	(ceramic near board) same (aluminum with via)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 18:58
S43	53	(ceramic near board) same (copper with vias)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 19:00
S42	53	(ceramic near board) same (copper with via)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 19:00
S41	770	(ceramic near board) same (copperwith via)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 19:00
S44	90	(ceramic near board) same (copper with (hole throughhole))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 19:06
S45	525	(ceramic near board) and (copper with (vias hole throughhole))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 19:08
S46	17	S45 and S31	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 19:09
S47	2	"20040016568".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 19:14
S48	179	S45 and (copper with (heat thermal))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 19:16

S49	27	(US-20040008459-$ or US-20010014029-$ or US-20060175630-$ or US-20030164549-$).did. or (US-6656770-$ or US-6020597-$ or US-5844311-$ or US-5920120-$ or US-5886408-$ or US-4985805-$ or US-6281573-$ or US-5977568-$ or US-6147400-$ or US-5912803-$ or US-5587882-$ or US-5523586-$ or US-5268814-$ or US-5155661-$ or US-4609937-$ or US-5014777-$ or US-5089936-$ or US-7250674-$ or US-6437240-$ or US-6858892-$ or US-5177670-$).did. or (US-3443168-$ or US-3551758-$).did.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/14 19:57
S50	27	(US-20040008459-$ or US-20010014029-$ or US-20060175630-$ or US-20030164549-$).did. or (US-6656770-$ or US-6020597-$ or US-5844311-$ or US-5920120-$ or US-5886408-$ or US-4985805-$ or US-6281573-$ or US-5977568-$ or US-6147400-$ or US-5912803-$ or US-5587882-$ or US-5523586-$ or US-5268814-$ or US-5155661-$ or US-4609937-$ or US-5014777-$ or US-5089936-$ or US-7250674-$ or US-6437240-$ or US-6858892-$ or US-5177670-$).did. or (US-3443168-$ or US-3551758-$).did.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/14 19:59
S51	2	S50 and (back-to-back)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 20:01
S52	6	"756340".ap.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 20:18
S53	6	"314139".ap.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/14 20:19